

RoHS Compliant Product
A suffix of "-C" specifies halogen free

DESCRIPTION

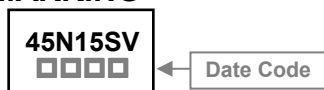
The SSD45N15SV-C is the highest performance N-ch MOSFETs with extreme high cell density, which provides excellent $R_{DS(ON)}$ and gate charge for most of the synchronous buck converter applications.

The SSD45N15SV-C meet the RoHS and Green Product requirement with full function reliability approved.

FEATURES

- High Speed Power Switching
- Super Low Gate Charge
- Green Device Available

MARKING



PACKAGE INFORMATION

Package	MPQ	Leader Size
TO-252	2.5K	13 inch

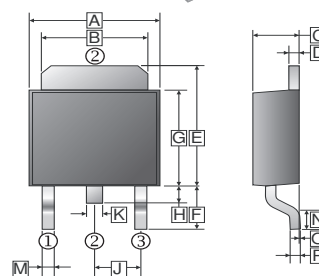
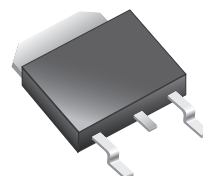
ORDER INFORMATION

Part Number	Type
SSD45N15SV-C	Lead (Pb)-free and Halogen-free

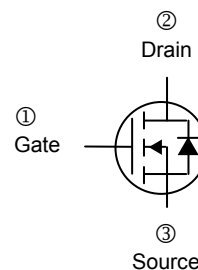
ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DS}	150	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹ @ $V_{GS}=10V$	I_D	$T_C=25^\circ C$	45
		$T_C=100^\circ C$	28
Pulsed Drain Current ³	I_{DM}	100	A
Total Power Dissipation	P_D	52	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55~150	$^\circ C$
Thermal Resistance Ratings			
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	62.5	$^\circ C/W$
Thermal Resistance Junction-Ambient ²		110	
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	2.4	

TO-252(D-Pack)



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	6.30	6.90	J	2.30 REF.	
B	4.95	5.53	K	0.89 REF.	
C	2.10	2.50	M	0.45	1.14
D	0.40	0.90	N	1.55	Typ.
E	6.00	7.70	O	0	0.15
F	2.90	REF.	P	0.58	REF.
G	5.40	6.40			
H	0.60	1.20			



ELECTRICAL CHARACTERISTICS ($T_J=25^\circ C$ unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions	
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	150	-	-	V	$V_{GS}=0V, I_D=250\mu A$	
Gate-Threshold Voltage	$V_{GS(th)}$	2	-	4	V	$V_{DS}=V_{GS}, I_D=250\mu A$	
Gate-Source Leakage Current	I_{GSS}	-	-	± 100	nA	$V_{GS}=\pm 20V$	
Drain-Source Leakage Current	I_{DSS}	$T_J=25^\circ C$	-	-	1	uA	$V_{DS}=120V, V_{GS}=0$
		$T_J=55^\circ C$	-	-	100		$V_{DS}=120V, V_{GS}=0$
Static Drain-Source On-Resistance ⁴	$R_{DS(ON)}$	-	16	19.5	m Ω	$V_{GS}=10V, I_D=15A$	
Total Gate Charge	Q_g	-	27	-	nC	$I_D=15A$ $V_{DS}=75V$ $V_{GS}=10V$	
Gate-Source Charge	Q_{gs}	-	9	-			
Gate-Drain Charge	Q_{gd}	-	2	-			
Turn-on Delay Time	$T_{d(on)}$	-	12	-	nS	$V_{DD}=75V$ $I_D=15A$ $V_{GS}=10V$ $R_G=10\Omega$	
Rise Time	T_r	-	4	-			
Turn-off Delay Time	$T_{d(off)}$	-	24	-			
Fall Time	T_f	-	5	-			
Input Capacitance	C_{iss}	-	2275	-	pF	$V_{GS}=0V$ $V_{DS}=75V$ $f=1MHz$	
Output Capacitance	C_{oss}	-	165	-			
Reverse Transfer Capacitance	C_{rss}	-	5.5	-			
Source-Drain Diode							
Diode Forward Voltage ⁴	V_{SD}	-	-	1.2	V	$I_S=15A, V_{GS}=0V$	
Continuous Source Current ¹	I_S	-	-	45	A		
Pulsed Source Current ³	I_{SM}	-	-	100	A		
Reverse Recovery Time	T_{rr}	-	60	-	nS	$I_S=15A, di/dt=100A/us$	
Reverse Recovery Charge	Q_{rr}	-	120	-	nC	$V_{DD}=75V$	

Notes:

1. Surface mounted on a 1 inch² FR-4 board with 20Z copper.
2. When mounted on Min. copper pad.
3. Pulse width limited by maximum junction temperature , pulse width $\leq 300us$, duty cycle $\leq 2\%$
4. The data tested by pulsed, pulse width $\leq 300us$, duty cycle $\leq 2\%$.

CHARACTERISTIC CURVES

Fig 1. Typical Output Characteristics

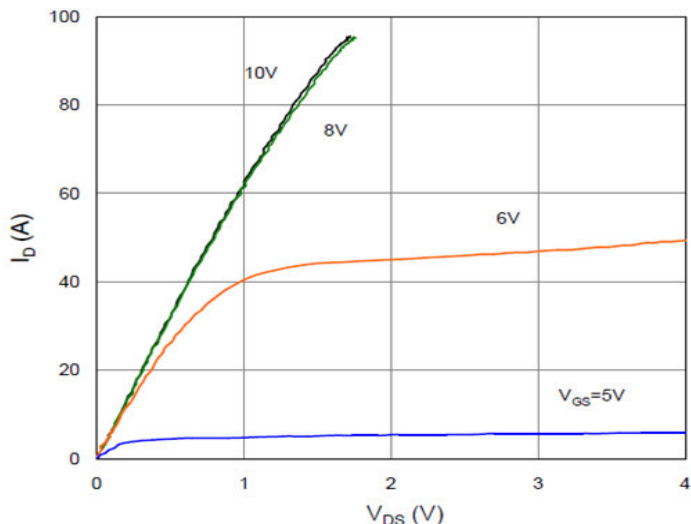


Figure 2. On-Resistance vs. Gate-Source Voltage

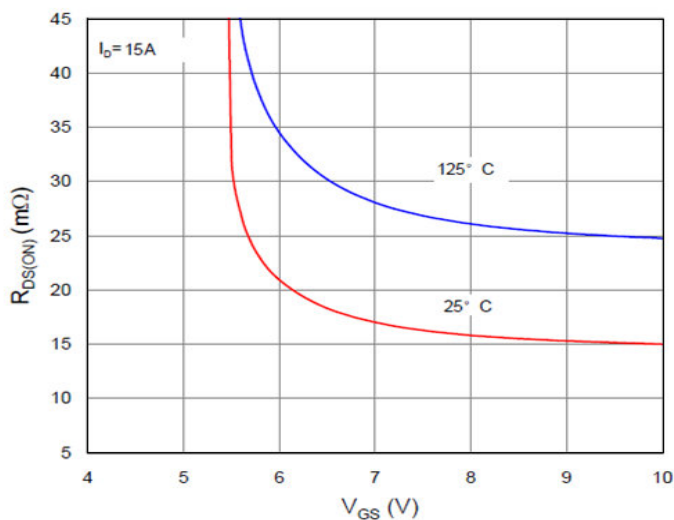


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

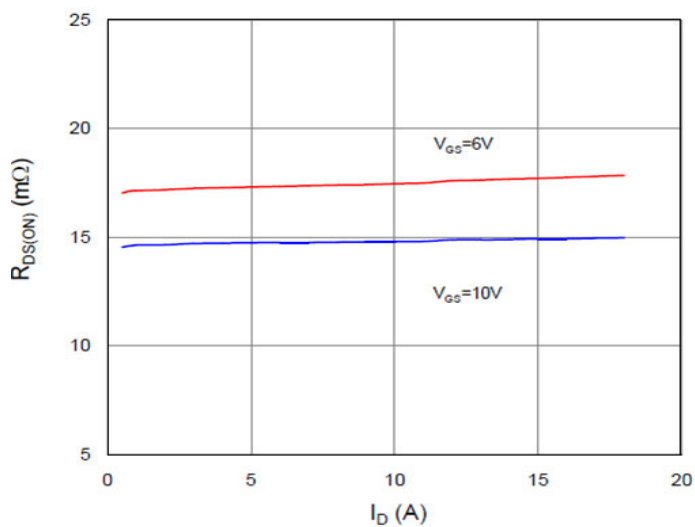


Figure 4. Normalized On-Resistance vs. Junction Temperature

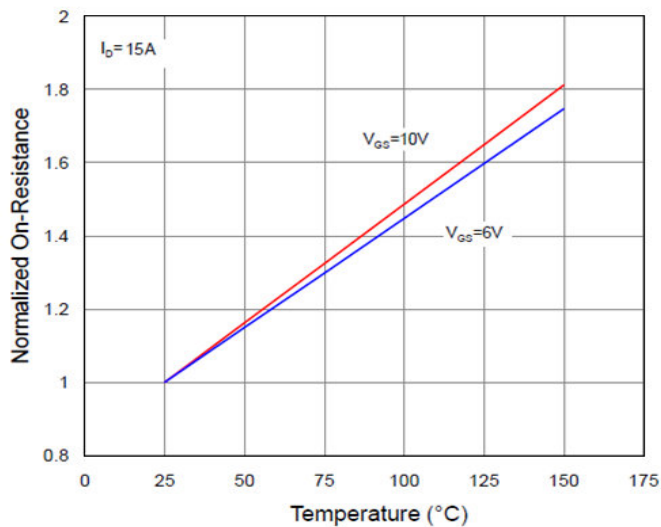


Figure 5. Typical Transfer Characteristics

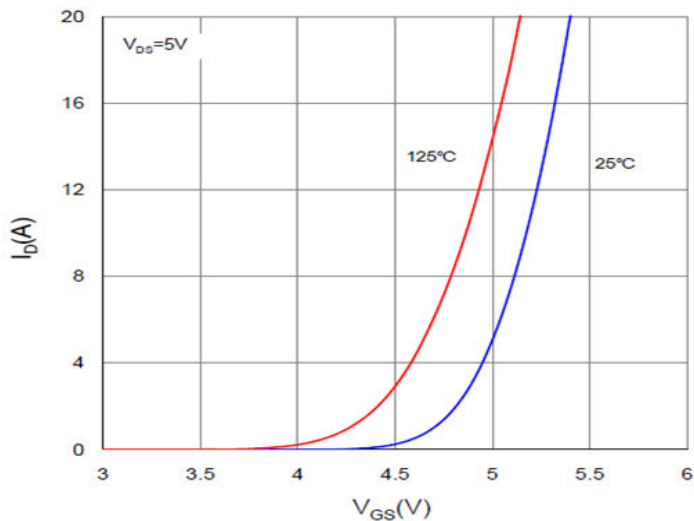
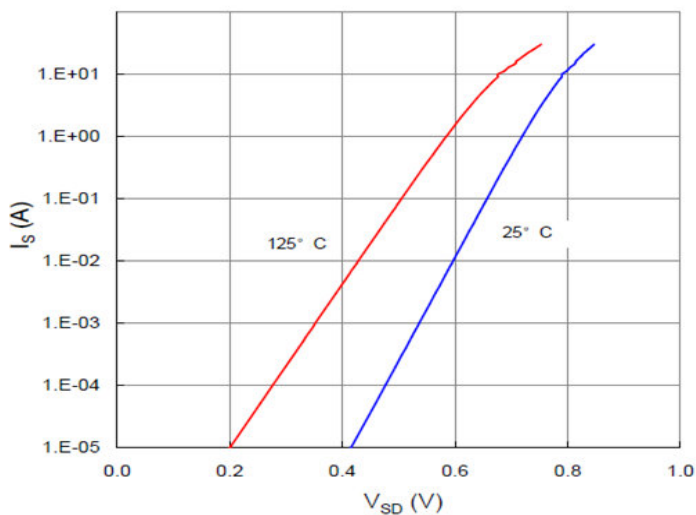


Figure 6. Typical Source-Drain Diode Forward Voltage



CHARACTERISTIC CURVES

Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

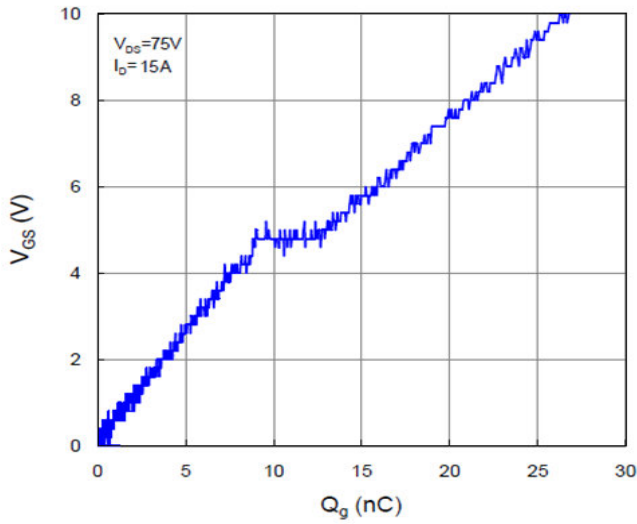


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

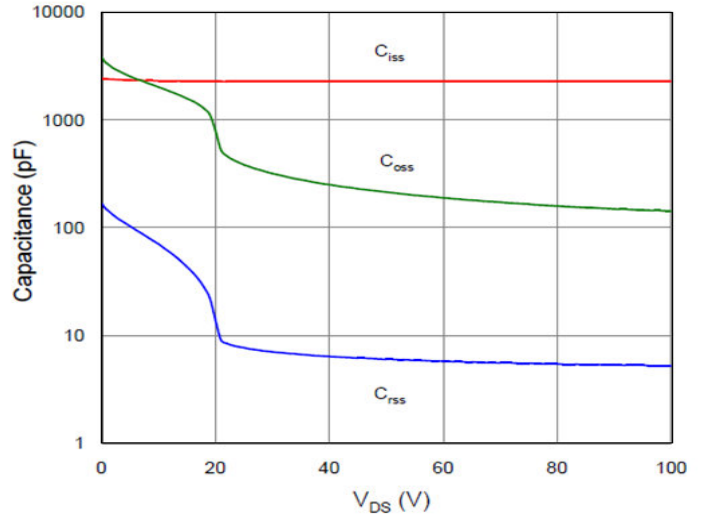


Figure 9. Maximum Safe Operating Area

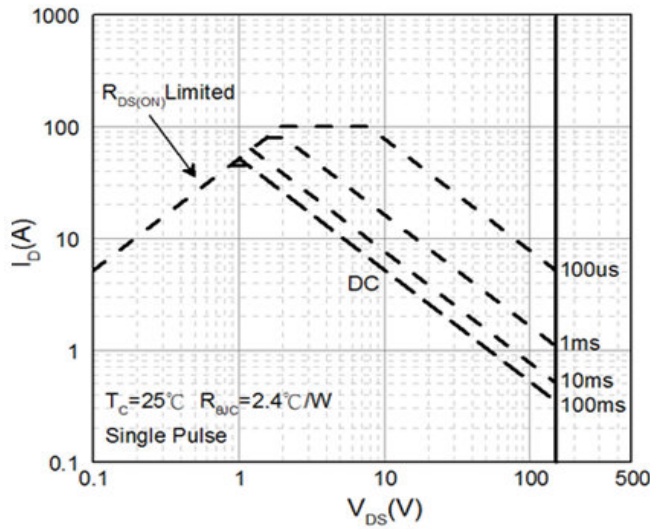


Figure 10. Maximum Drain Current vs. Case Temperature

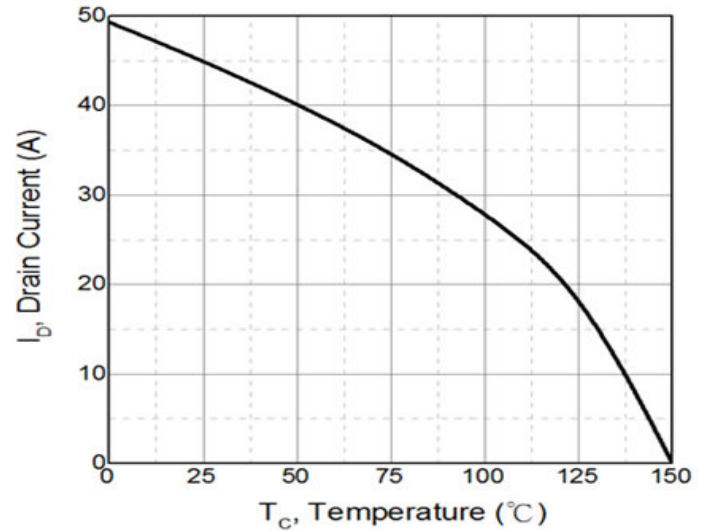


Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case

